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S/N: 09/832,884



6/2/2003

DOCKET NO.: L/M-102-DIV

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: St v M. Danzig r, et al.

Serial No.: 09/832,884
Divisional of 09/321,565

Art Unit: 2829

Filed: April 12, 2001

Examiner: Evan T. Pert

For: Method and Apparatus for Evaluating a Known Good Die Using
Both Wire Bond and Flip-Chip Interconnects

AMENDMENT

*Entered
1/31/03
armer*

US Patent & Trademark Office
2011 South Clark Place
Customer Window, Mail Stop: AF
Crystal Plaza Two, Lobby, Room 1B03
Arlington, VA 22202

Sir:

This Amendment is responsive to the Final Office Action dated April 1, 2003. Claims 1 - 8, 10 and 44 are pending in this application and have been rejected. Applicant hereby requests reconsideration in light of the following amendments in the claims.

Please amend this application as follows: